



AMENDMENT UNDER 37 CFR 1.116
EXPEDITED PROCEDURE-
EXAMINING GROUP 3652

AGJ
12/04/02
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LNEJ

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Yoo, Woo Sik
Assignee: WaferMasters, Inc.
Title: Wafer Transport System and Method
Serial No.: 09/838,083 Filing Date: April 19, 2001
Examiner: Charles A. Fox Group Art Unit: 3652
Docket No.: M-11439 US

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Washington, D. C. 20231

GROUP 3600

RESPONSE TO FINAL OFFICE ACTION

Dear Sir:

In response to the Final Office Action dated September 24, 2002, Applicants submit the following amendments and remarks.

IN THE CLAIMS

The following is a clean version of the entire set of pending claims. In accordance with 37 C.F.R. §1.121(c)(1)(ii), Attachment A provides a marked-up version of the claim containing the newly introduced changes.

1. (Amended) A method for transporting semiconductor wafers comprising: providing a processing system including a transport module and process chamber; extending a semiconductor wafer transport device from said transport module into an adjacently positioned Front Opening Unified Pod (FOUP) while said FOUP remains a separate component from said processing system; and removing at least one semiconductor wafer from said FOUP using said wafer transport device.